# nexperia

## **Product Change Notification**

**Issue date:** 02 Nov 2022

Effective date: 01 May 2023

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.

Quality

## Improved leadless 8 pad packages to achieve zero delamination in ATSN, Malaysia (Automotive)

#### Change Category

[] Wafer Fab Process [] Wafer Fab Material s [] Wafer Fab Location	[ ] Assembl y Process [X] Assembl y Materials [ ] Assembl y Location	<ul> <li>Product Marking</li> <li>Mechanical</li> <li>Specification</li> <li>Packing/Shipping/Labelin</li> <li>g</li> </ul>	[X] Test Location [ ] Test Process [ ] Test Equipmen t	[ ] Design [ ] Errata [ ] Electrical spec./Tes t coverage	
--	---	---	--	--	--

## Details of this change

CN-202210024F

Improved BOM of leadless 8 pad packages to achieve zero delamination in ATSN (Nexperia Assembly & Test Plant Seremban Malaysia) for automotive customers

- BOM change for zero delamination performance
- Enhanced mould compound
- Introduced rough PPF inner leadframe

- Changed lead finish from Sn to enhanced NiPdAu (alignment with packages which were released since 2015)

- No change of die
- No change of diffusion fab location
- No change of assembly location
- Introduce wafer test (WT) at UTL

Qualification in accordance to the Automotive Electronics Council: - AEC-Q100-rev. H Stress Test Qualification for Integrated Circuits

SQR\_PCN\_CN-202210024F.pdf: <u>https://qcm.nexperia.com/Document/DOC-545934/SQR\_PCN\_CN-202210024F.pdf</u>

#### Why do we implement this change?

To improve the intrinsic quality

#### Identification of affected products

The changed products can be identified by backward traceability of the product marking date code as well as on the reel and box labels

#### **Management summary**

- Improved leadless 8 pad packages to achieve zero delamination for automotive customers

- Introduce wafer test (WT) at UTL (UTAC Thai Limited Bangkok Thailand)

- For automotive products / customers

## Product availability

#### Production

Planned first shipment: 01 May 2023

Existing inventory will be shipped until depleted

#### Sample information

Samples are available upon request

## Impact

No impact to the product's functionality anticipated

#### Data sheet revision

No impact to existing datasheet

#### Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 02 Dec 2022. Lack of acknowledgement of the PCN constitutes acceptance of the change.

## **Additional information**

View Change Notification Online

#### Remarks

No change in data sheet electrical specification, test limits and distributions
 No assembly location change - No wafer fab location change - No wafer fab process change - Samples are available upon request via Helpdesk+ from
 BG Analog & Logic ICs sample store in Nijmegen The Netherlands

### **Contact and support**

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: <u>pcn@nexperia.com</u>

In case of distribution, please contact you distribution partner.

## About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

You have received this email because you are a designated contact or subscribed to Nexperia Quality Notifications. Nexperia shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

If you would like to adjust your mailing preferences, please click here.